



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD65R600E6	Issued	01. April 2021
MA#	MA001152180		
Package	PG-TO252-3-313	Weight*	319.03 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.294	1.03	1.03	10325	10325
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		462	
	non noble metal	copper	7440-50-8	147.096	46.11	46.17	461077	461678
wire	non noble metal	aluminium	7429-90-5	0.623	0.20	0.20	1952	1952
encapsulation	inorganic material	zinc oxide	1314-13-2	1.405	0.44		4403	
	miscellaneous	miscellaneous	-	7.023	2.20		22013	
	plastics	epoxy resin	-	21.069	6.60		66040	
	inorganic material	silicon dioxide	60676-86-0	110.961	34.78	44.02	347813	440269
lead finish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11723	11723
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4453	4464
solder	non noble metal	tin	7440-31-5	0.060	0.02		188	
	noble metal	silver	7440-22-4	0.075	0.02		235	
	non noble metal	lead	7439-92-1	2.863	0.90	0.94	8976	9399
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.01	6.02	60112	60190
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com